



PK173 (v1.5) April 26, 2013

# 100% Material Declaration Data Sheet for VQ100 Package

**Average Weight: 0.5392 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.017360</b>	<b>3.220</b>
	Silicon (Si)	7440-21-3	100.00		0.017360	
<b>Die Attach</b>					<b>0.025760</b>	<b>4.778</b>
	Silver (Ag)	7440-22-4	72.00		0.018547	
	Epoxy Resin	Trade Secret	15.00		0.003864	
	Anhydride	Trade Secret	10.00		0.002576	
	1,4-Butanedioldiglycidyl ether	2425-79-8	3.00		0.000773	
<b>Mold Compound</b>					<b>0.347130</b>	<b>64.385</b>
	Epoxy Resin	Trade secret	7.00		0.024299	
	Phenol Resin	Trade secret	5.00		0.017357	
	Carbon Black	1333-86-4	0.30		0.001041	
	Fused Silica	60676-86-0	87.70		0.304433	
<b>Leadframe</b>					<b>0.140910</b>	<b>26.136</b>
	Copper (Cu)	7440-50-8	98.28		0.138486	
	Chromium (Cr)	7440-47-3	0.25		0.000352	
	Tin (Sn)	7440-31-5	0.25		0.000352	
	Zinc (Zn)	7440-66-6	0.22		0.000310	
	Silver (Ag)	7440-22-4	1.00		0.001409	
<b>Solder Plating</b>					<b>0.005910</b>	<b>1.096</b>
	Tin (Sn)	7440-31-5	85.00		0.005024	
	Lead (Pb)	7439-92-1	15.00		0.000887	
<b>Gold Wire</b>					<b>0.002081</b>	<b>0.386</b>
	Gold (Au)	7440-57-5	99.00		0.002060	
	Palladium	7440-05-3	1.00		0.000021	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/20/06	1.0	Initial Xilinx release.
07/05/06	1.1	100% Material Declaration
10/05/06	1.2	Corrected component descriptions
11/18/11	1.3	Updated component weights and descriptions
08/24/12	1.4	Updated CAS # in Die Attach
04/26/13	1.5	Updated CAS Description in Die Attach

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